



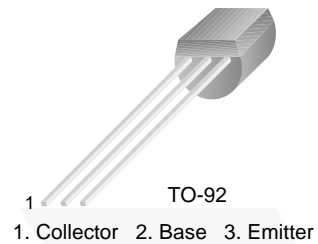
April 2014

BC556 / BC557 / BC558 / BC559 / BC560

PNP Epitaxial Silicon Transistor

Features

- Switching and Amplifier
- High-Voltage: BC556, $V_{CEO} = -65\text{ V}$
- Low-Noise: BC559, BC560
- Complement to BC546, BC547, BC548, BC549, and BC550



Ordering Information

Part Number	Marking	Package	Packing Method
BC556ABU	BC556A	TO-92 3L	Bulk
BC556ATA	BC556A	TO-92 3L	Ammo
BC556BTA	BC556B	TO-92 3L	Ammo
BC556BTF	BC556B	TO-92 3L	Tape and Reel
BC556BTFR	BC556B	TO-92 3L	Tape and Reel
BC557ATA	BC557A	TO-92 3L	Ammo
BC557BTA	BC557B	TO-92 3L	Ammo
BC557BTF	BC557B	TO-92 3L	Tape and Reel
BC558BTA	BC558B	TO-92 3L	Ammo
BC559BTA	BC559B	TO-92 3L	Ammo
BC559CTA	BC559C	TO-92 3L	Ammo
BC560CTA	BC560C	TO-92 3L	Ammo

BC556 / BC557 / BC558 / BC559 / BC560 — PNP Epitaxial Silicon Transistor

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit	
V_{CBO}	Collector-Base Voltage	BC556	-80	V
		BC557 / BC560	-50	
		BC558 / BC559	-30	
V_{CEO}	Collector-Emitter Voltage	BC556	-65	V
		BC557 / BC560	-45	
		BC558 / BC559	-30	
V_{EBO}	Emitter-Base Voltage	-5	V	
I_C	Collector Current (DC)	-100	mA	
P_C	Collector Power Dissipation	500	mW	
T_J	Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-65 to +150	$^\circ\text{C}$	

Electrical Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{CBO}	Collector Cut-Off Current	$V_{CB} = -30\text{ V}, I_E = 0$			-15	nA
h_{FE}	DC Current Gain	$V_{CE} = -5\text{ V}, I_C = -2\text{ mA}$	110		800	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = -10\text{ mA}, I_B = -0.5\text{ mA}$		-90	-300	mV
		$I_C = -100\text{ mA}, I_B = -5\text{ mA}$		-250	-650	
$V_{BE(sat)}$	Collector-Base Saturation Voltage	$I_C = -10\text{ mA}, I_B = -0.5\text{ mA}$		-700		mV
		$I_C = -100\text{ mA}, I_B = -5\text{ mA}$		-900		
$V_{BE(on)}$	Base-Emitter On Voltage	$V_{CE} = -5\text{ V}, I_C = -2\text{ mA}$	-600	-660	-750	mV
		$V_{CE} = -5\text{ V}, I_C = -10\text{ mA}$			-800	
f_T	Current Gain Bandwidth Product	$V_{CE} = -5\text{ V}, I_C = -10\text{ mA}, f = 10\text{ MHz}$		150		MHz
C_{ob}	Output Capacitance	$V_{CB} = -10\text{ V}, I_E = 0, f = 1\text{ MHz}$			6	pF
NF	Noise Figure	BC556 / BC557 / BC558		2	10	dB
		BC559 / BC560		1	4	
		BC559	1.2	4.0		
		BC560	1.2	2.0		

h_{FE} Classification

Classification	A	B	C
h_{FE}	110 ~ 220	200 ~ 450	420 ~ 800

Typical Performance Characteristics

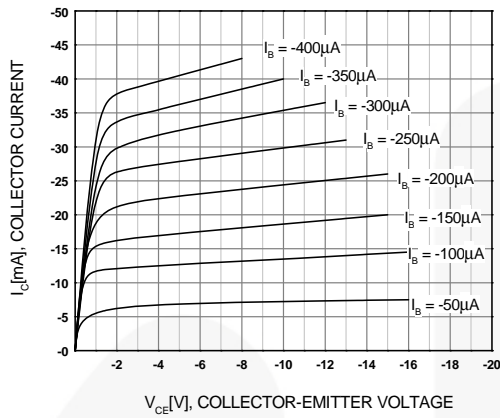


Figure 1. Static Characteristic

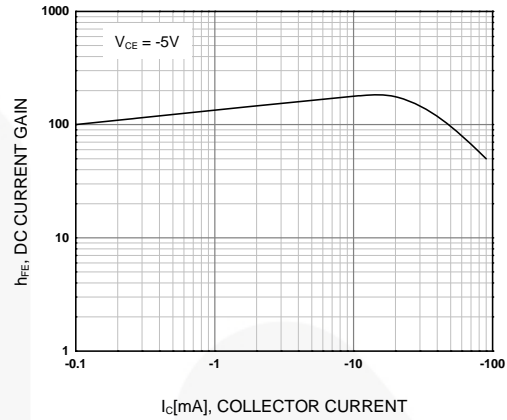


Figure 2. DC Current Gain

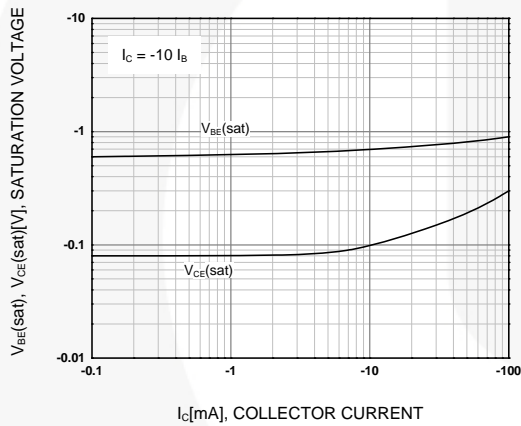


Figure 3. Base-Emitter Saturation Voltage and Collector-Emitter Saturation Voltage

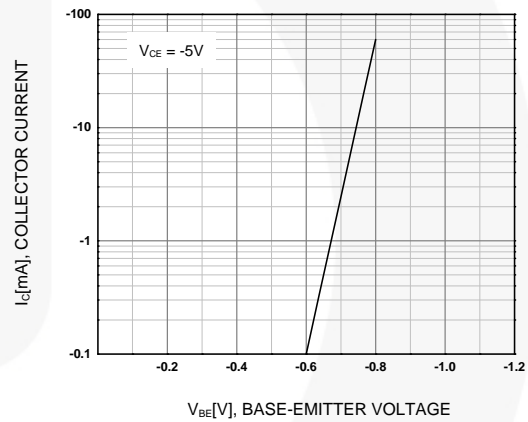


Figure 4. Base-Emitter On Voltage

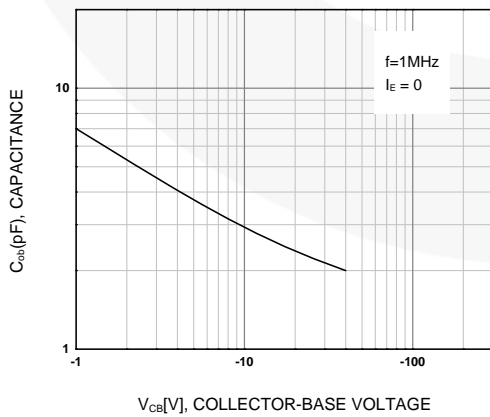


Figure 5. Collector Output Capacitance

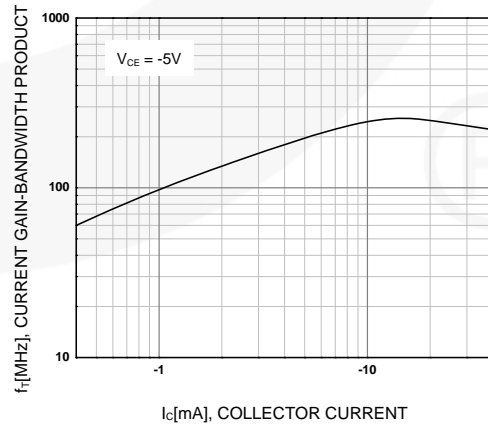
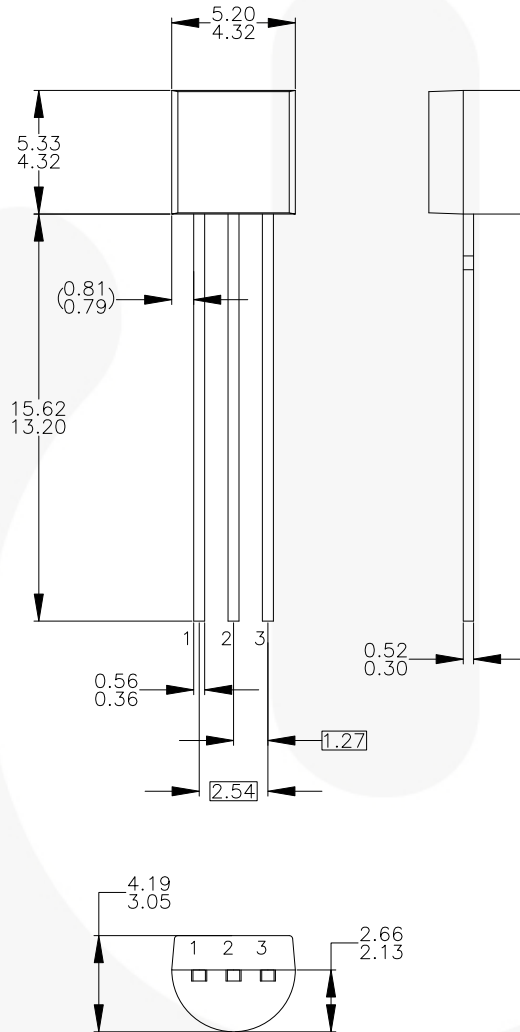


Figure 6. Current Gain Bandwidth Product

Physical Dimensions

TO-92 (Bulk)



NOTES: UNLESS OTHERWISE SPECIFIED

- A) DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M-1994.
- D) TO-92 (92,94,96,97,98) PIN CONFIGURATION:

PIN	92			94			96			97			98		
	P	F	M	P	F	M	B	F	M	P	F	M	P	F	M
1	E	S	S	E	S	S	B	D	G	C	G	D	C	G	D
2	B	D	G	C	G	D	E	S	S	B	D	G	E	S	S
3	C	G	D	B	D	G	C	G	D	E	S	S	B	D	G

LEGEND:

- P - BIPOLAR
- F - JFET
- M - DMOS
- E - EMITTER
- B - BASE
- C - COLLECTOR
- D - DRAIN
- S - SOURCE
- G - GATE

- E) FOR PACKAGE 92, 94, 96, 97 AND 98: PIN CONFIGURATION DRAIN "D" AND SOURCE "S" ARE INTERCHANGEABLE AT JFET "F" OPTION.
- F) DRAWING FILENAME: MKT-ZA03DREV3.

Figure 7. 3-LEAD, TO92, JEDEC TO-92 COMPLIANT STRAIGHT LEAD CONFIGURATION (OLD TO92AM3)

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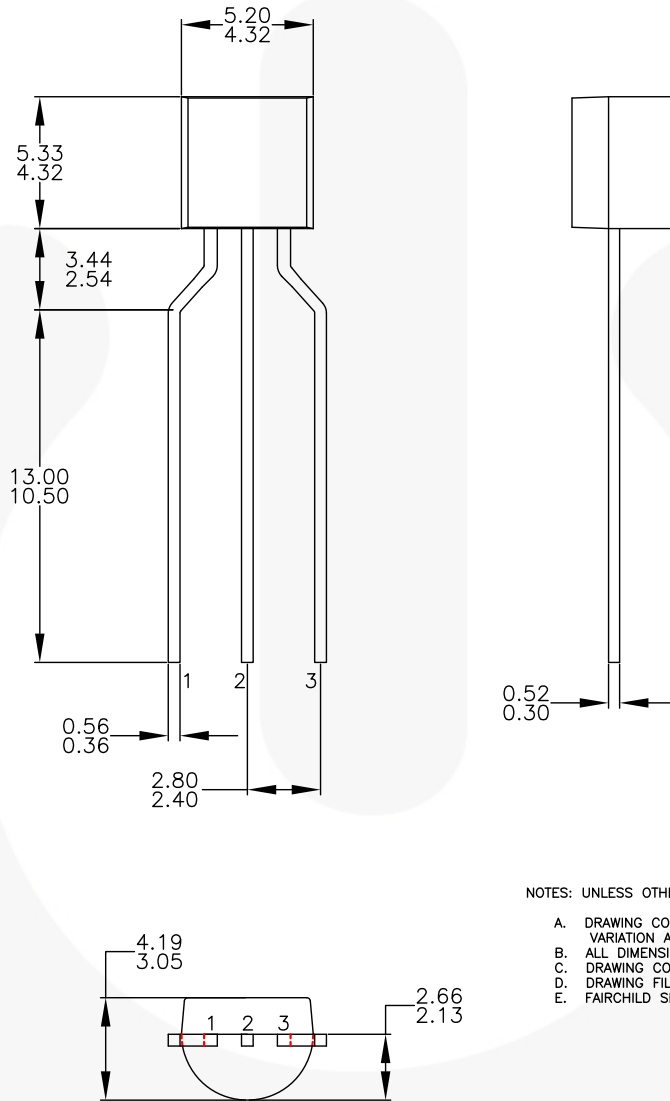
<http://www.fairchildsemi.com/dwg/ZA/ZA03D.pdf>

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area:

http://www.fairchildsemi.com/packaging_dwg/PKG-ZA03D_BK.pdf

Physical Dimensions (Continued)

TO-92 (Ammo, Tape and Reel)



- NOTES: UNLESS OTHERWISE SPECIFIED
- A. DRAWING CONFORMS TO JEDEC MS-013, VARIATION AC.
 - B. ALL DIMENSIONS ARE IN MILLIMETERS.
 - C. DRAWING CONFORMS TO ASME Y14.5M-2009.
 - D. DRAWING FILENAME: MKT-ZA03FREV3.
 - E. FAIRCHILD SEMICONDUCTOR.

Figure 8. 3-LEAD, TO92, MOLDED 0.200 IN LINE SPACING LEAD FORM (J61Z OPTION)

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http://www.fairchildsemi.com/packaging_dwg/PKG-ZA03F_BK.pdf



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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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